

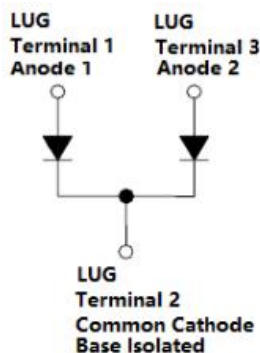
503CMQ600 ULTRAFAST RECTIFIER



Features

- 175 °C T_J operation
- Center tap module
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Base plate: Nickel plated; Terminals: Nickel plated
- The terminal hardware is supplied with the module.
- The mounting hardware is not supplied. Recommended is the use of ¼-20 or M6 screws with spring washer.
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- High current switching power supply
- Plating power supply
- Free-Wheeling diodes
- Reverse battery protection
- Converters
- UPS System
- Welding

Maximum Ratings(limiting values, at 25 °C unless otherwise specified)

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V_{RRM}	-	600	V
Working Peak Reverse Voltage	V_{RWM}			
DC Blocking Voltage	V_R			
Average Rectified Forward Current	$I_{F(AV)}$	50% duty cycle @T _C =117°C, rectangular wave form	250(Per leg)	A
			500(Per device)	
Peak One Cycle Non-Repetitive Surge Current(Per leg)	I_{FSM}	8.3 ms, half Sine pulse	2000	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per leg)*	V_{F1}	@ 250A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	1.11	2.0	V
Reverse Current (Per leg)*	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25\text{ }^\circ\text{C}$	0.4	100	μA
Reverse Recovery Time(Per leg)	t_{rr}	IF=500mA, IR=1A,and Irm=250mA	150	200	ns

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification		Units
Junction Temperature	T_J	-	-55 to +175		$^\circ\text{C}$
Storage Temperature	T_{stg}	-	-55 to +175		$^\circ\text{C}$
Typical Thermal Resistance Junction to Case (per leg)	$R_{\theta JC}$	DC operation	0.30		$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Case (per package)	$R_{\theta JC}$	DC operation	0.15		$^\circ\text{C/W}$
Typical Thermal Resistance, Case to Heat Sink	$R_{\theta CS}$	Mounting surface, smooth and greased	0.05		$^\circ\text{C/W}$
Approximate Weight	wt	-	110		g
Mounting Torque	T_M	-	Mounting Torque	3.84(min) 4.80(max)	Nm
			Terminal Torque	2.35(min) 3.43(max)	
Case Style	PRM4 Isolated				

Ratings and Characteristics Curves

Figure 1
Typical Forward Characteristics

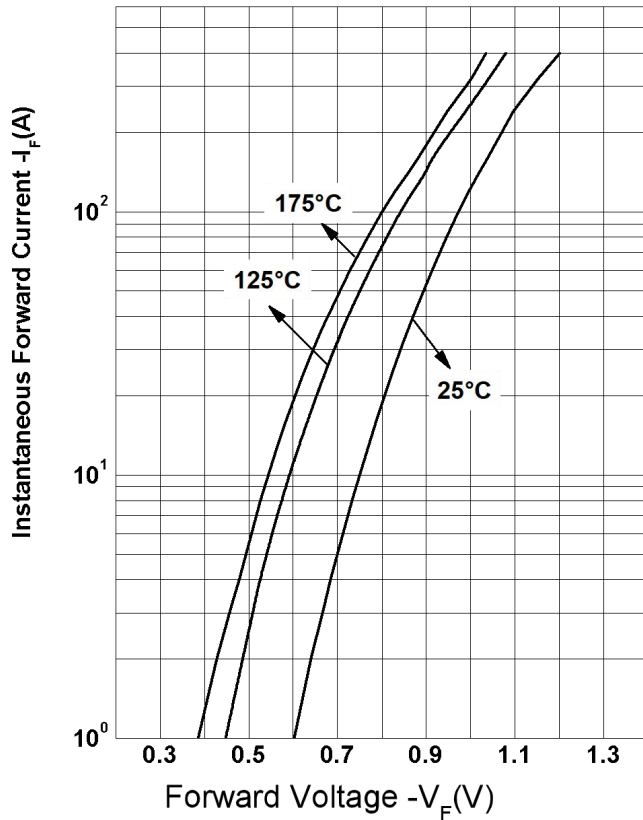


Figure 2
Typical Reverse Characteristics

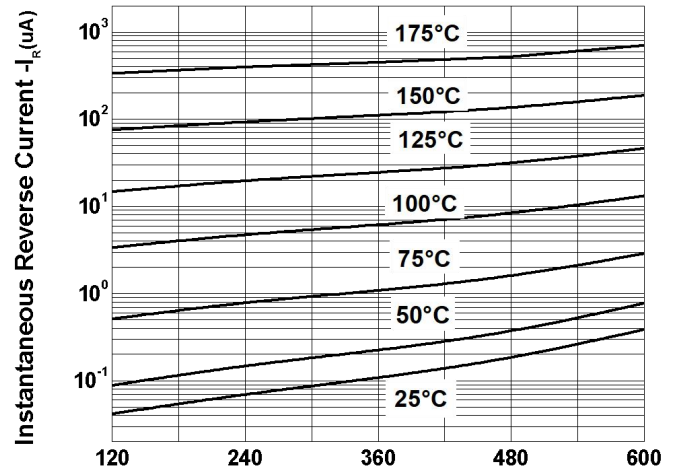
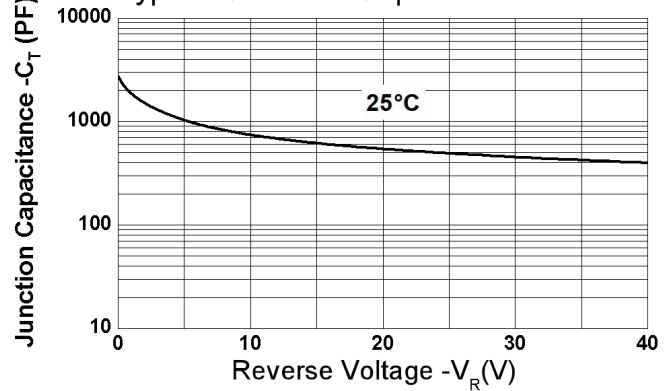


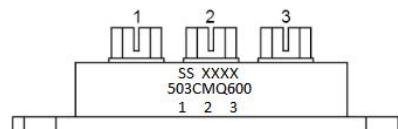
Figure 3
Reverse Voltage $-V_R$ (V)
Typical Junction Capacitance



Ordering Information

Device	Package	Shipping
503CMQ600	PRM4 (Isolated) (Pb-Free)	9pcs/ box

Marking Diagram

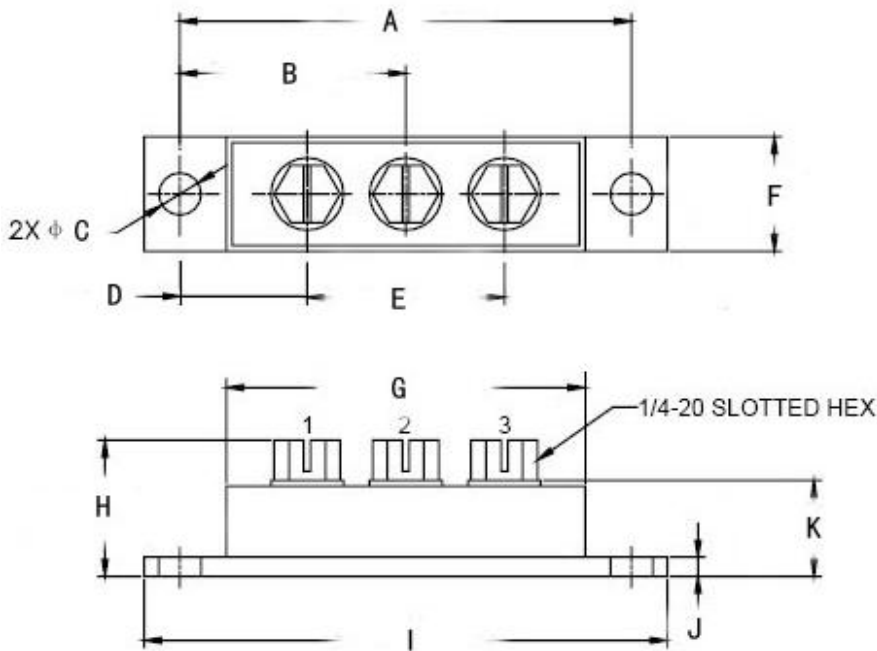


Where XXXX is YYWW

1st row SS YYWW
 2nd row 503CMQ600
 SS = SS
 YY = Year
 WW = Week

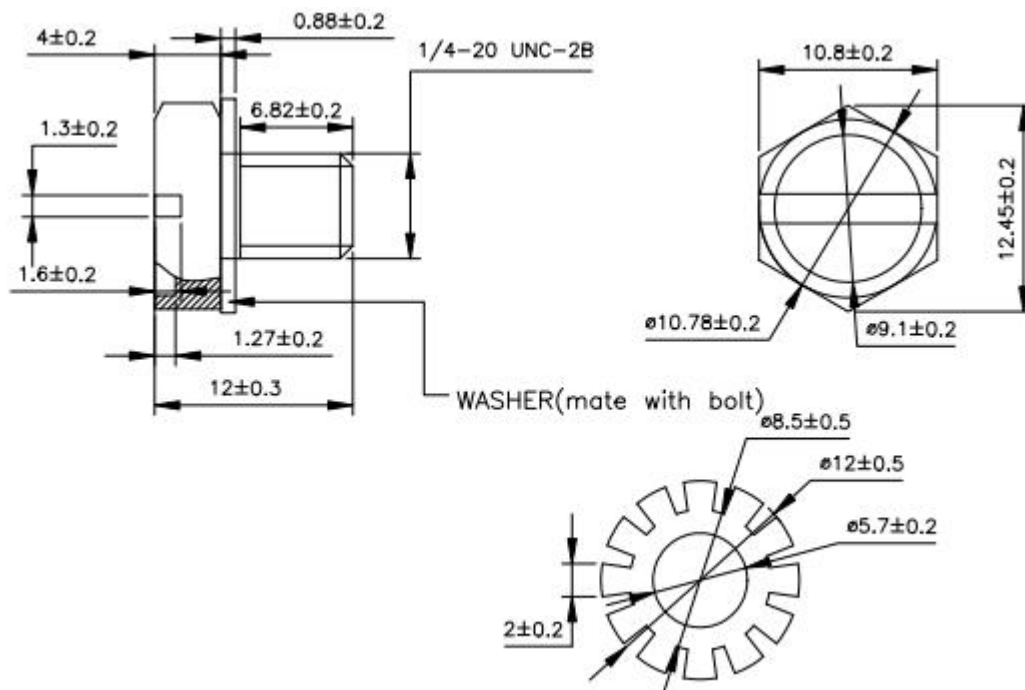
Cautions: Molding resin
 Epoxy resin UL:94V-0

Mechanical Dimensions PRM4 Isolated(Millimeters/Inches)



SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	78.74	81.28	3.100	3.200
B	37.47	42.55	1.475	1.675
C	6.89	7.69	0.271	0.303
D	19.51	24.59	0.768	0.968
E	33.02	38.10	1.300	1.500
F	17.78	20.32	0.700	0.800
G	60.96	64.77	2.400	2.550
H	17.56	23.55	0.691	0.927
I	90.17	92.71	3.550	3.650
J	3.02	3.68	0.119	0.145
K	15.75	17.50	0.620	0.689

1/4-20 screws (Millimeters)



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